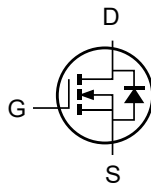
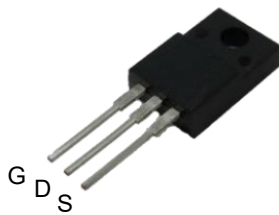


450V N-Channel Power MOSFET

MPR11N45CTF
TO-220F



Features

- Low gate charge
- Low Ciss
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- AC to DC Converters
- Telecom, Solar

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
V(BR)DSS	Drain-Source breakdown voltage	450	V
VGS	Gate-Source voltage	± 30	V
ID	Continuous drain current	11	A
IDM	Pulse drain current tested ①	40	A
IS	Continuous Diode Forward Current	10	A
EAS	Avalanche energy, single pulsed ②	580	mJ
dv/dt	Reverse Diode dV/dt ③	5	V/ns
PD	Power Dissipation	40	W
T _{STG} , T _J	Storage and Junction Temperature Range	-55 to 150	°C

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

② L=10mH, I_{AS}=10.8A, starting T_J=25°C.

③ I_{SD}=10A, dI/dt≤100A/us, V_{DD}≤BV_{DSS}, starting T_J=25°C, Pulse width≤300us; duty cycle≤2%

Thermal Characteristics

Symbol	Parameter	Typical	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	3.13	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	450	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =450V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±30V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.0	--	4.0	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =5A	--	0.5	0.75	Ω
g _{fs}	Forward Transconductance	V _{DS} =15V, I _D =5A	--	10	--	S

Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	--	1620	--	pF
C _{oss}	Output Capacitance		--	154	--	pF
C _{rss}	Reverse Transfer Capacitance		--	8.4	--	pF
Q _g	Total Gate Charge	V _{DS} =400V, I _D =10A , V _{GS} =10V	--	32	--	nC
Q _{gs}	Gate-Source Charge		--	7.9	--	nC
Q _{gd}	Gate-Drain Charge		--	12	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DD} =250V, I _D =10A, R _G =10Ω,	--	26	--	ns
Tr	Turn-on Rise Time		--	20	--	ns
Td(off)	Turn-Off Delay Time		--	52	--	ns
Tf	Turn-Off Fall Time		--	21	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

I _{SM}	Pulsed Diode Forward Current		--	--	40	A
V _{SD}	Forward on voltage	I _S =10A, V _{GS} =0V	--	--	1.5	V
T _{rr}	Reverse Recovery Time	I _S =10A, V _{GS} =0V	--	411	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	--	2.588	--	uC

Typical Characteristics

Fig 1. Typical Output Characteristics

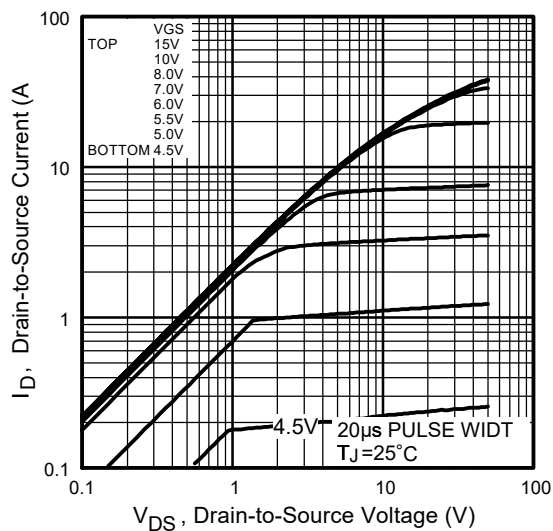


Fig 2. Typical Output Characteristics

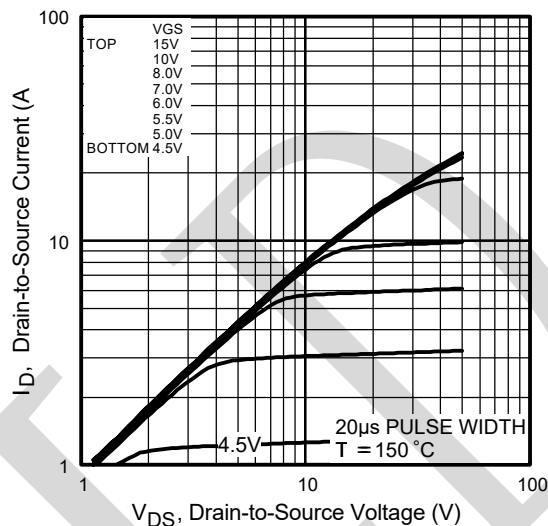


Fig 3. Typical Transfer Characteristics

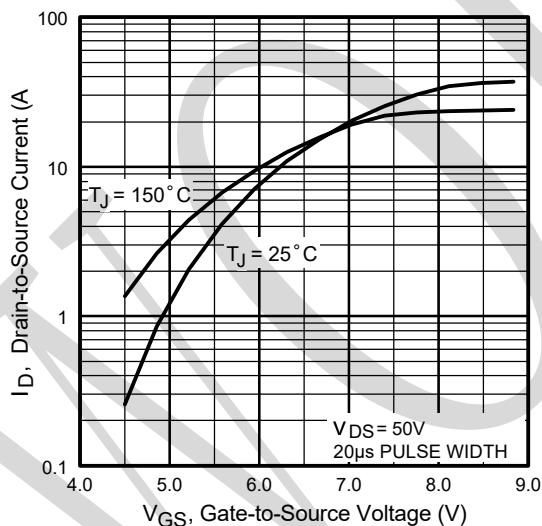
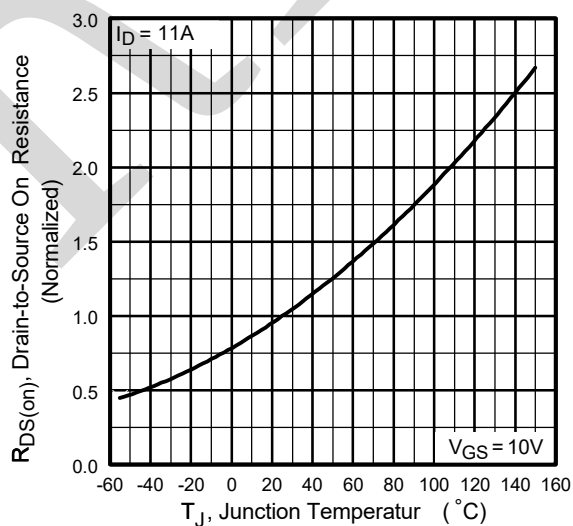


Fig 4. Normalized On-Resistance Vs. Temperature



Typical Characteristics

Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

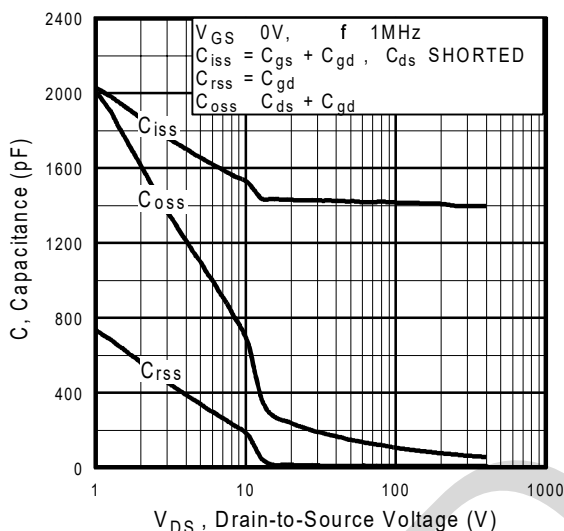


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

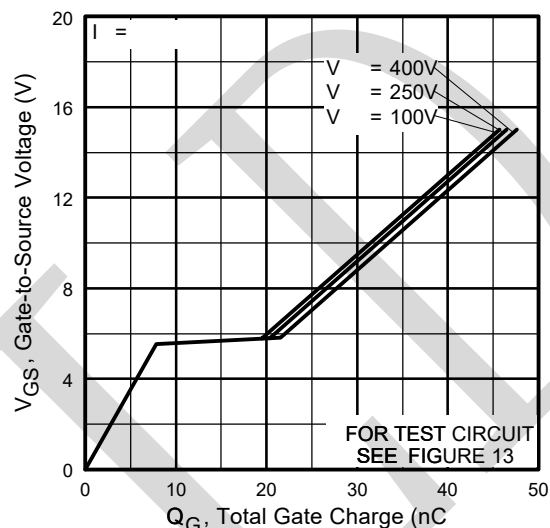


Fig 7. Typical Source-Drain Diode Forward Voltage

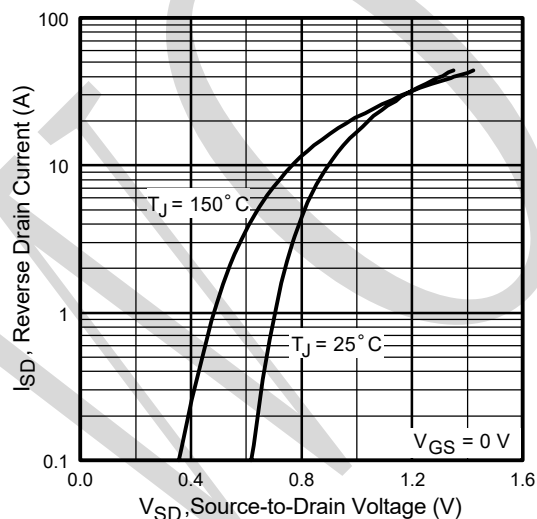
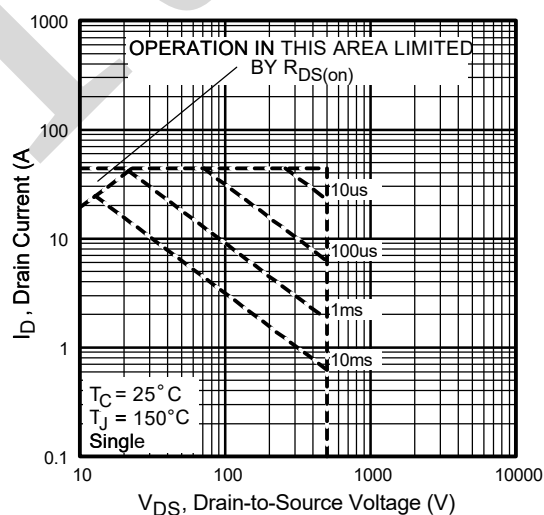


Fig 8. Maximum Safe Operating Area



Typical Characteristics

Fig 9. Maximum Drain Current Vs. Case Temperature

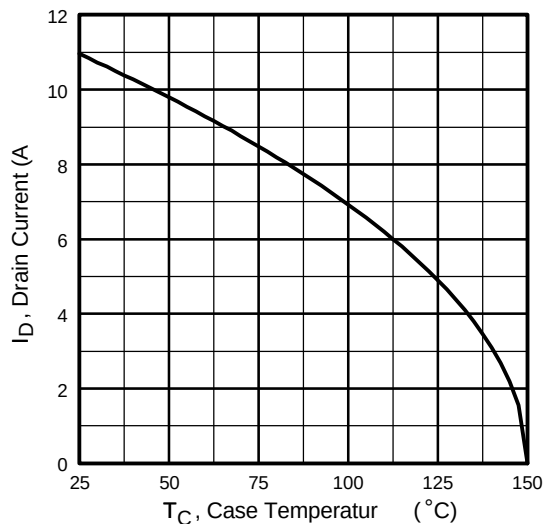


Fig 10. Maximum Avalanche Energy Vs. Drain Current

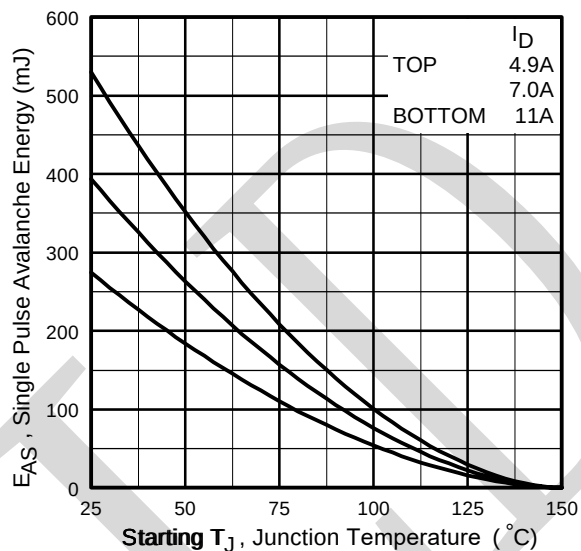
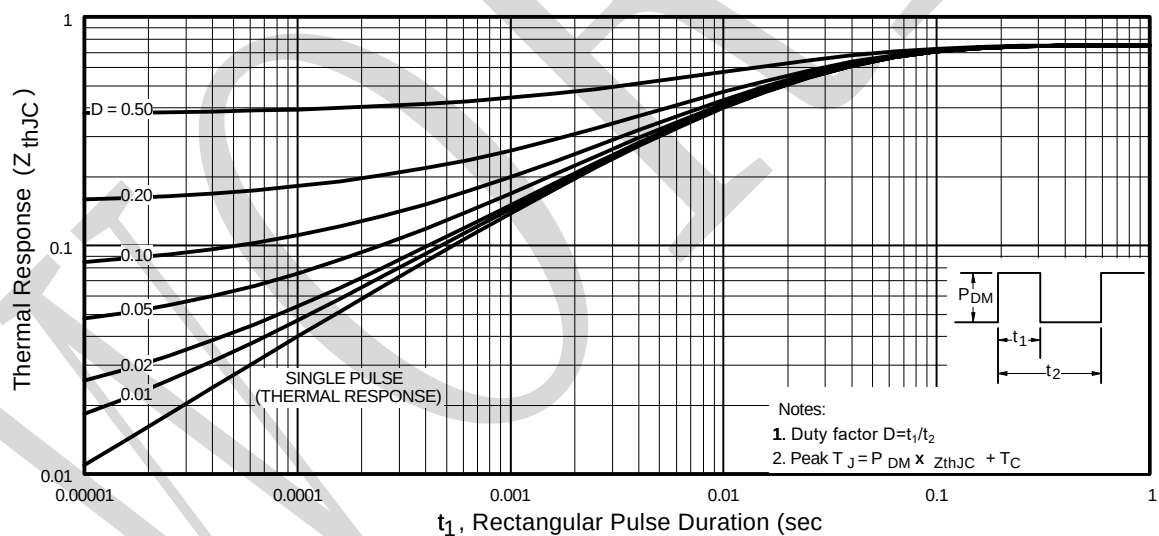


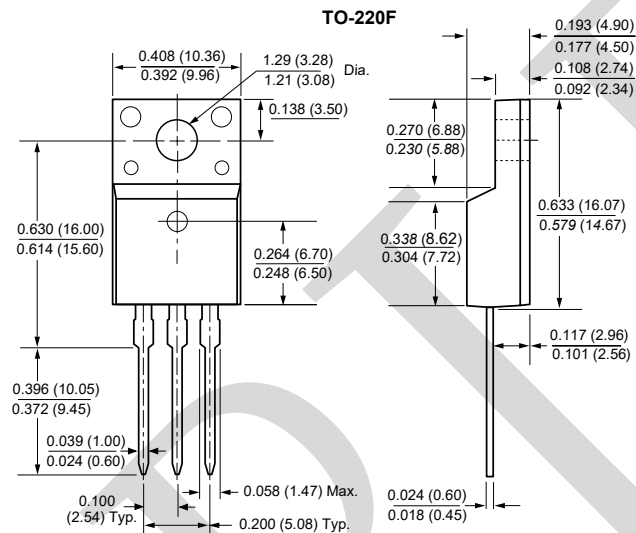
Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



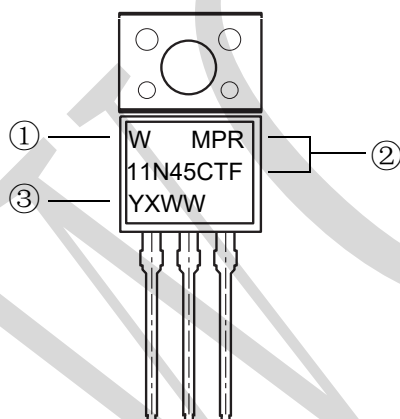
PACKAGE OUTLINE DIMENSIONS

TO-220F Package Information

Note:unit mm



Marking Information



- ① W : Company's trademark
- ② Product model : MPR11N45CTF
- ③ PDC information :

Y X WW

WW:Week code(01 to 53)

X:Internal identification code

Y:Year code(ex:0=2020)